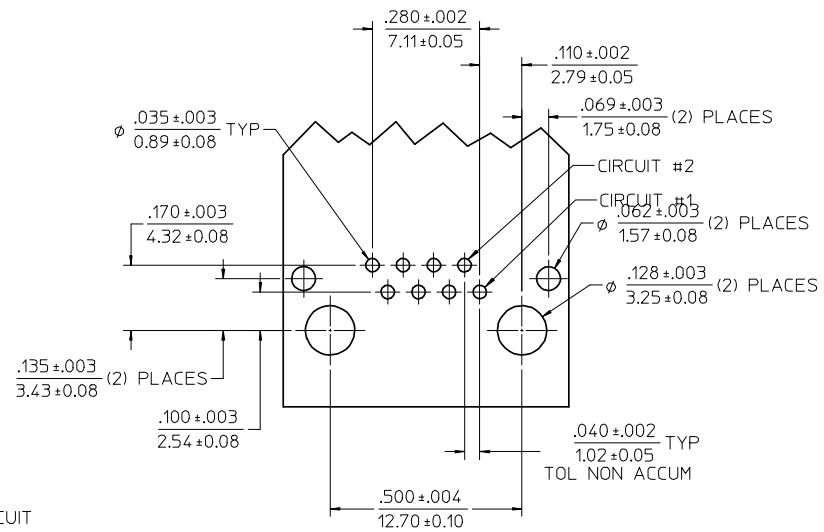
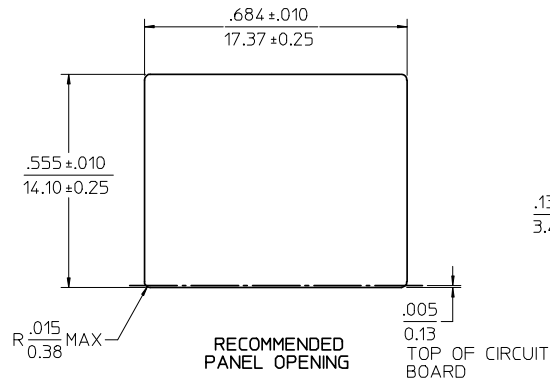
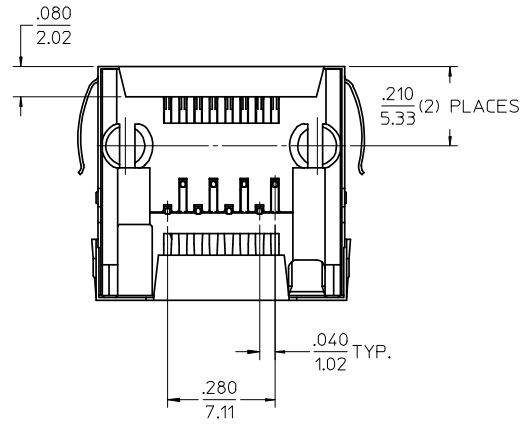
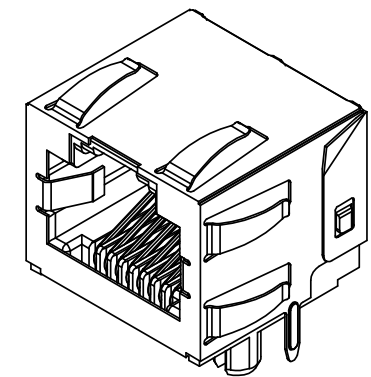
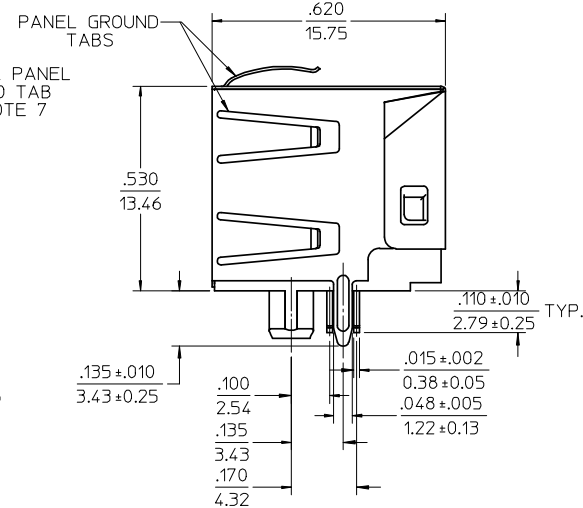
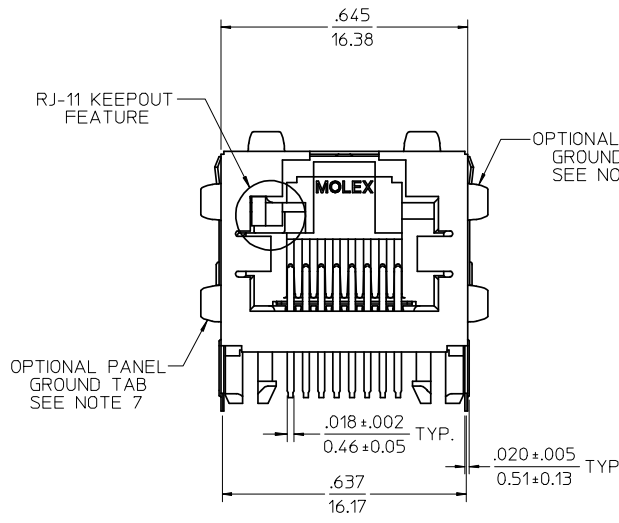


PC BOARD LAYOUT
COMPONENT SIDE OF BOARD
RECOMMENDED PCB THICKNESS: .062/1.57

- NOTES:
- 1) MATERIAL:
HOUSING: NYLON(PA), GLASS FILLED, UL94V-0, COLOR: BLACK
TERMINALS: PHOSPHOR BRONZE
 - 2) FINISH:
TERMINALS:
SELECT GOLD IN CONTACT AREA: 50 MICROINCHES (1.27 MICROMETERS) MIN.,
*SELECT TIN IN PC TAIL AREA: 100 MICROINCHES (2.54 MICROMETERS) MIN.,
WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES (1.27 MICROMETERS) MIN.
*THE PRIMARY SHIPPING CARTON WILL BE LABELED "COMPLIANT TO ROHS DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC".
CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH TIN-LEAD IN THE PC TAILS.
 - 3) PRODUCT SPECIFICATION AND PROCESSING PARAMETERS: PS-43860-003.
 - 4) PACKAGING SPECIFICATION:
CONNECTOR ASSEMBLIES PACKAGED IN EXTRUDED TUBES PER MOLEX PACKAGING SPECIFICATION PK-43860-004.
 - 5) ALL UNTOLERANCED DIMENSIONS ARE SHOWN FOR REFERENCE ONLY.
 - 6) CONFORMS TO FCC REGULATION PART 68.5 FOR MODULAR JACKS.
 - 7) THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPECIFICATION PS-45499-002.

ADD NOTE 7 EC NO: UCP2008-0965 DRWN: BELL 2007/11/08 CHKD: SCHMIDT 2007/12/04 APPR: FSMITH 2007/12/05	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE IN/MM		SCALE 4:1	DESIGN UNITS INCH	THIRD ANGLE PROJECTION	
		mm	INCH	DRAWN BY MKAMAR	DATE 00/03/07	TITLE RJ-45 INVERTED MODULAR JACK ASSEMBLY WITH RJ-11 KEEPOUT FEATURE			
		4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	CHECKED BY MKAMAR	DATE 00/03/07				
		2 PLACES ± --- ± ---	1 PLACE ± --- ± ---	APPROVED BY JROBERTS	DATE 00/03/07	MOLEX INCORPORATED			
ANGULAR ±1/2°		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. 446200001	DOCUMENT NO. SD-44620-001	SHEET NO. 1 OF 4		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	

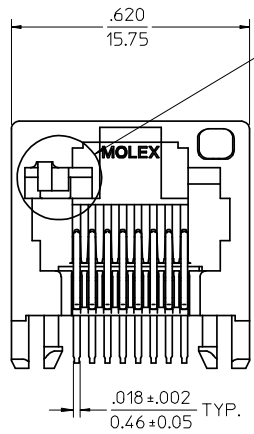


PC BOARD LAYOUT
COMPONENT SIDE OF BOARD
RECOMMENDED PCB THICKNESS: .062/1.57

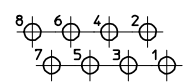
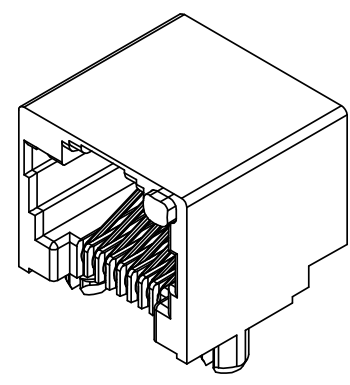
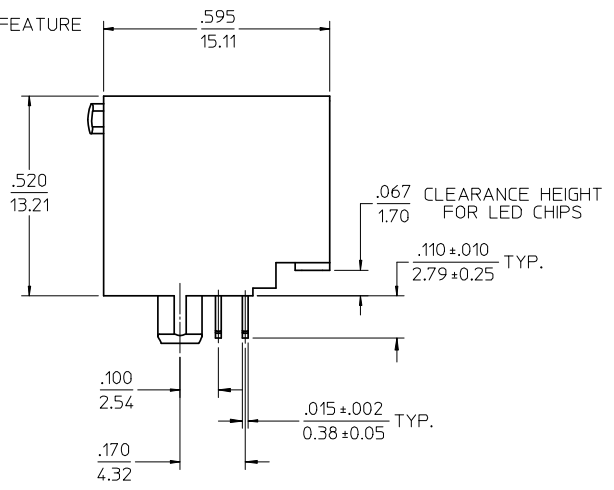
- NOTES:
- MATERIAL:
HOUSING: NYLON(IPA), GLASS FILLED, UL94V-0, COLOR: BLACK
TERMINALS: PHOSPHOR BRONZE
SHIELD: BRASS
 - FINISH:
TERMINALS:
SELECT GOLD IN CONTACT AREA: 50 MICROINCHES (1.27 MICROMETERS) MIN.,
*SELECT TIN IN PC TAIL AREA: 100 MICROINCHES (2.54 MICROMETERS) MIN.,
WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES (1.27 MICROMETERS) MIN.
SHIELD:
*100 MICROINCHES (2.54 MICROMETERS) NICKEL OVER 50 MICROINCHES
(1.27 MICROMETERS) COPPER UNDERPLATE, PCB GROUND TABS DIPPED IN TIN
*THE PRIMARY SHIPPING CARTON WILL BE LABELED "COMPLIANT TO ROHS
DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC".
CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH TIN-LEAD
IN THE PC TAILS AND/OR SHIELD.
 - PRODUCT SPECIFICATION AND PROCESSING PARAMETERS: PS-43860-003.
 - PACKAGING SPECIFICATION:
CONNECTOR ASSEMBLIES PACKAGED IN THERMOFORMED TRAYS PER MOLEX
PACKAGING SPECIFICATION PK-43860-005.
 - ALL UNTOLERANCED DIMENSIONS ARE SHOWN FOR REFERENCE ONLY.
 - CONFORMS TO FCC REGULATION PART 68.5 FOR MODULAR JACKS.
 - AVAILABLE WITH THE (2) SPECIFIED PANEL GROUND TABS OMITTED FOR
SIDE TO SIDE STACKABILITY, PER THE ASSEMBLY MATERIAL NUMBER TABLE.
 - THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC
SPECIFICATION PS-45499-002.

ASSEMBLY MATERIAL NUMBER	PANEL GROUND TABS
446200002	ALL
446200003	SEE NOTE 7

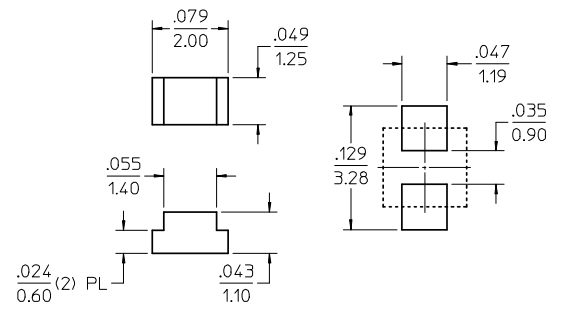
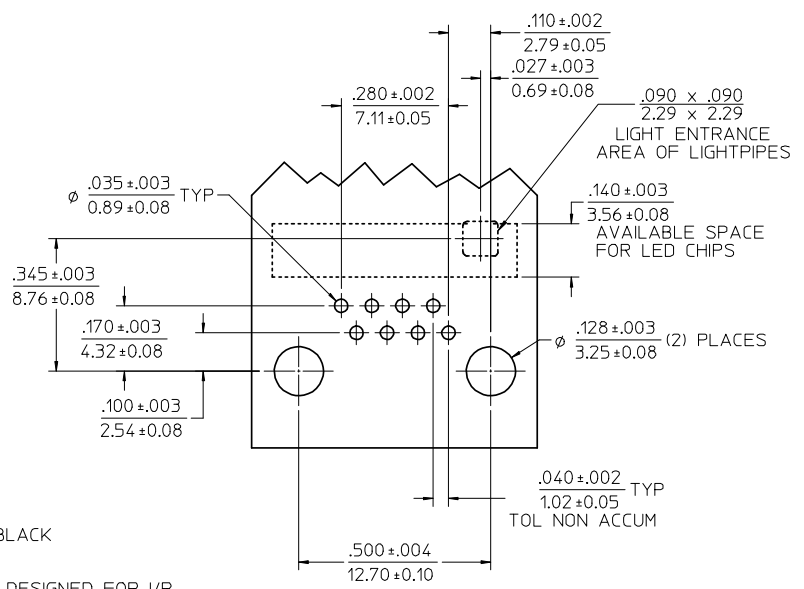
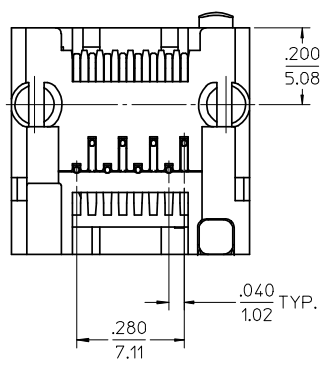
ADD NOTE 8 EC NO: UCP2008-0965 DRWN: BELL 2007/11/08 CHKD: LSCM/DT 2007/12/04 APPR: FSM/TH 2007/12/05	DESCRIPTION REV 1	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED) <table border="1"> <thead> <tr> <th></th> <th>mm</th> <th>INCH</th> </tr> </thead> <tbody> <tr> <td>4 PLACES ±</td> <td>---</td> <td>---</td> </tr> <tr> <td>3 PLACES ±</td> <td>---</td> <td>---</td> </tr> <tr> <td>2 PLACES ±</td> <td>---</td> <td>---</td> </tr> <tr> <td>1 PLACE ±</td> <td>---</td> <td>---</td> </tr> </tbody> </table>		mm	INCH	4 PLACES ±	---	---	3 PLACES ±	---	---	2 PLACES ±	---	---	1 PLACE ±	---	---	DIMENSION STYLE IN/MM	SCALE 4:1	DESIGN UNITS INCH	THIRD ANGLE PROJECTION
			mm	INCH																		
		4 PLACES ±	---	---																		
		3 PLACES ±	---	---																		
2 PLACES ±	---	---																				
1 PLACE ±	---	---																				
DRAWN BY MKAMAR 00/03/07			DATE 00/03/07		RJ-45 INVERTED MODULAR JACK ASSEMBLY WITH RJ-11 KEEPOUT FEATURE																	
CHECKED BY MKAMAR 00/03/07			DATE 00/03/07																			
APPROVED BY JROBERTS 00/03/07			DATE 00/03/07		MOLEX INCORPORATED																	
MATERIAL NO. SEE CHART			DOCUMENT NO. SD-44620-001																			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE C		SHEET NO. 2 OF 4																	
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION																						



RJ-11 KEEPUT FEATURE



TYPICAL PC TERMINAL HOLE LAYOUT
SCALE 5:1



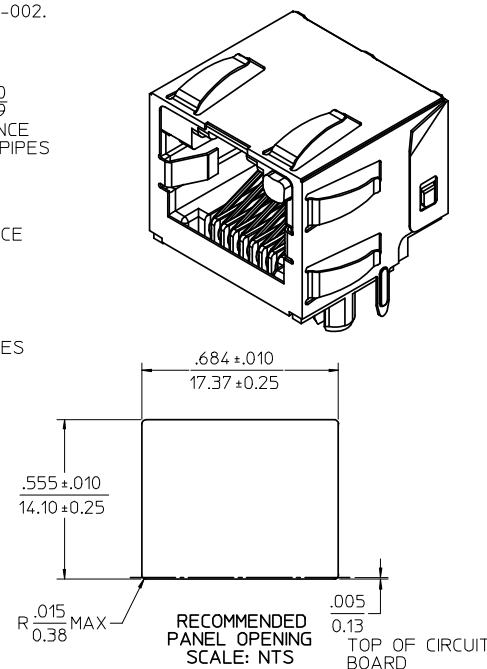
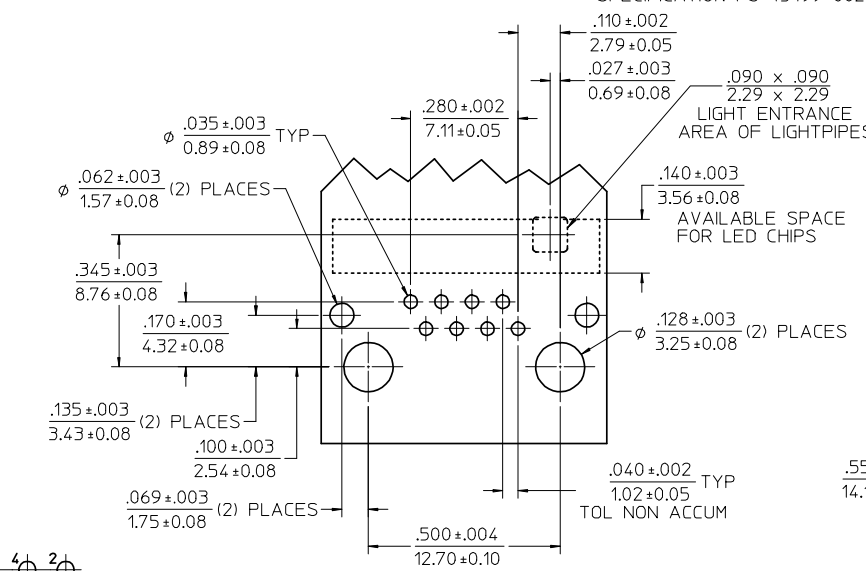
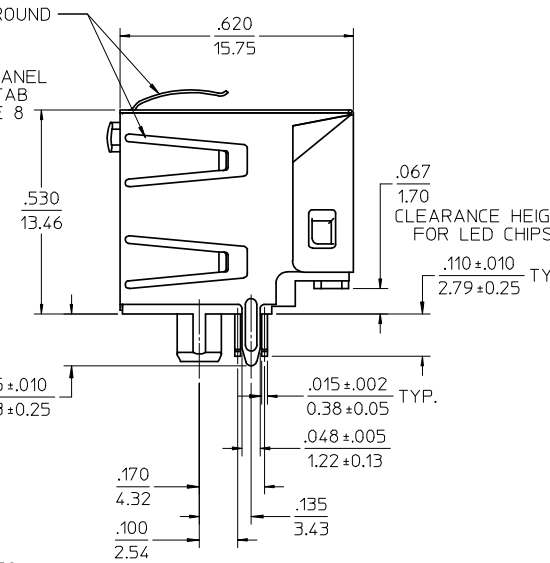
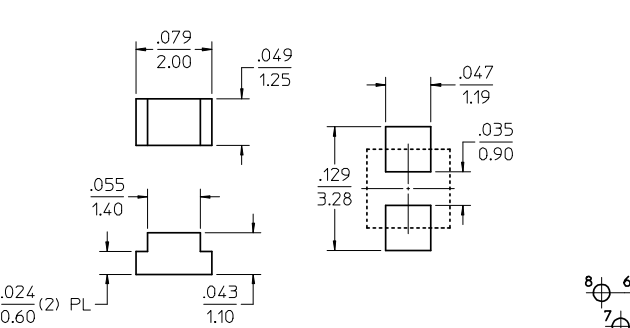
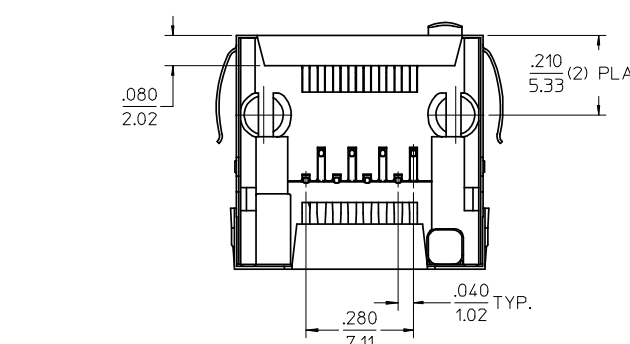
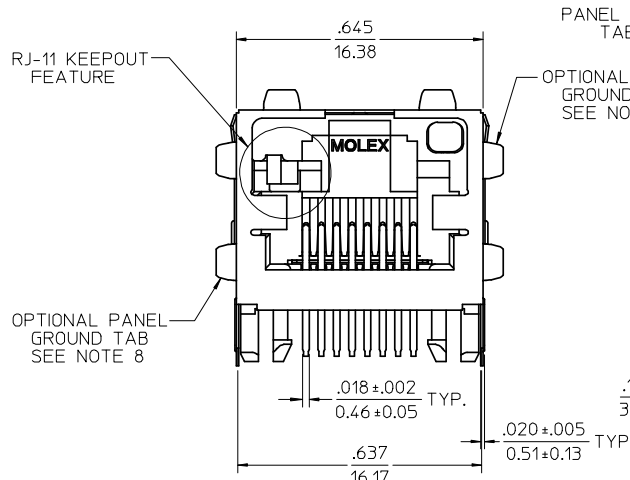
RECOMMENDED SMT
LED SOLDER PATTERN
SCALE 10:1
(SEE NOTE 8)

PC BOARD LAYOUT
COMPONENT SIDE OF BOARD
RECOMMENDED PCB THICKNESS: .062/1.57

- NOTES:
- MATERIAL:
HOUSING: NYLON(PA), GLASS FILLED, UL94V-0, COLOR: BLACK
TERMINALS: PHOSPHOR BRONZE
LIGHT PIPES:
POLYCARBONATE-WAVE OR HAND SOLDER ONLY (NOT DESIGNED FOR 1/8 REFLOW OR CONVECTION REFLOW SOLDER PROCESSES)
POLYSULFONE-MAXIMUM REFLOW TEMPERATURE: 400°F (205°C)
 - FINISH:
TERMINALS:
SELECT GOLD IN CONTACT AREA: 50 MICRONS (1.27 MICROMETERS) MIN.,
*SELECT TIN IN PC TAIL AREA: 100 MICRONS (2.54 MICROMETERS) MIN.,
WITH OVERALL NICKEL UNDERPLATE: 50 MICRONS (1.27 MICROMETERS) MIN.
*THE PRIMARY SHIPPING CARTON WILL BE LABELED "COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC".
CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH TIN-LEAD IN THE PC TAILS.
 - PRODUCT SPECIFICATION AND PROCESSING PARAMETERS: PS-43860-003.
 - PACKAGING SPECIFICATION:
CONNECTOR ASSEMBLIES PACKAGED IN EXTRUDED TUBES PER MOLEX PACKAGING SPECIFICATION PK-43860-004.
 - APPLICATION SPECIFICATION: AS-43860-001.
 - ALL UNTOLERANCED DIMENSIONS ARE SHOWN FOR REFERENCE ONLY.
 - CONFORMS TO FCC REGULATION PART 68.5 FOR MODULAR JACKS.
 - FOR CROSS REFERENCE OF RECOMMENDED LED'S, SEE MOLEX WEBSITE.
 - THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPECIFICATION PS-45499-002.

ASSEMBLY MATERIAL NUMBER	LIGHT PIPE MATERIAL
446201004	POLYCARBONATE
446201005	POLYSULFONE

ADD NOTE 5 & 9 EC NO: UCP2008-0965 DRWN: BELL 2007/11/08 CHKD: SCHMIDT 2007/12/04 APPR: FSMITH 2007/12/05 D2	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE IN/MM		SCALE 4:1	DESIGN UNITS INCH	THIRD ANGLE PROJECTION	
		4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± --- ± --- 1 PLACE ± --- ± ---	mm INCH DRAWN BY DATE MKAMAR 00/03/07 CHECKED BY DATE MKAMAR 00/03/07 APPROVED BY DATE JROBERTS 00/03/07	TITLE RJ-45 INVERTED MODULAR JACK ASSEMBLY WITH RJ-11 KEEPUT FEATURE					
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE CHART		DOCUMENT NO. SD-44620-001		SHEET NO. 3 OF 4	
		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							



- NOTES:
- MATERIAL: HOUSING: NYLON(PA), GLASS FILLED, UL94V-0, COLOR: BLACK; TERMINALS: PHOSPHOR BRONZE; SHIELD: BRASS; LIGHT PIPES: POLYCARBONATE-WAVE OR HAND SOLDER ONLY (NOT DESIGNED FOR I/R REFLOW OR CONVECTION REFLOW SOLDER PROCESSES); POLYSULFONE-MAXIMUM REFLOW TEMPERATURE: 400°F (205°C)
 - FINISH: TERMINALS: SELECT GOLD IN CONTACT AREA: 50 MICROINCHES (1.27 MICROMETERS) MIN.; SELECT TIN IN PC TAIL AREA: 100 MICROINCHES (2.54 MICROMETERS) MIN., WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES (1.27 MICROMETERS) MIN.; SHIELD: *100 MICROINCHES (2.54 MICROMETERS) NICKEL OVER 50 MICROINCHES (1.27 MICROMETERS) COPPER UNDERPLATE; PCB GROUND TABS DIPPED IN TIN; *THE PRIMARY SHIPPING CARTON WILL BE LABELED 'COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC'; CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH TIN-LEAD IN THE PC TAILS AND/OR SHIELD.
 - PRODUCT SPECIFICATION AND PROCESSING PARAMETERS: PS-43860-003.
 - PACKAGING SPECIFICATION: CONNECTOR ASSEMBLIES PACKAGED IN THERMOFORMED TRAYS PER MOLEX PACKAGING SPECIFICATION PK-43860-005.
 - APPLICATION SPECIFICATION: AS-43860-001
 - ALL UNTOLERANCED DIMENSIONS ARE SHOWN FOR REFERENCE ONLY.
 - CONFORMS TO FCC REGULATION PART 68.5 FOR MODULAR JACKS.
 - AVAILABLE WITH THE (2) SPECIFIED PANEL GROUND TABS OMITTED FOR SIDE TO SIDE STACKABILITY, PER THE ASSEMBLY MATERIAL NUMBER TABLE.
 - FOR CROSS REFERENCE OF RECOMMENDED LED'S, SEE MOLEX WEBSITE.
 - THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPECIFICATION PS-45499-002.

ASSEMBLY MATERIAL NUMBER	LIGHT PIPE MATERIAL	PANEL GROUND TABS
446201006	POLYCARBONATE	ALL
446201007	POLYCARBONATE	SEE NOTE 8
446201008	POLYSULFONE	ALL
446201009	POLYSULFONE	SEE NOTE 8

ADD NOTE 5 & 10	QUALITY SYMBOLS
EC NO: UCP2008-0965	▽=0
DRWN: BELL 2007/11/08	▽=0
CHKD: SCHMIDT 2007/12/04	
APPR: FSMITH 2007/12/05	
REV	DESCRIPTION
D2	

GENERAL TOLERANCES (UNLESS SPECIFIED)	
mm	INCH
4 PLACES ± ---	± ---
3 PLACES ± ---	± ---
2 PLACES ± ---	± ---
1 PLACE ± ---	± ---
ANGULAR ± 1/2°	

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE	
IN/MM	
DRAWN BY	DATE
DATE	00/03/07
CHECKED BY	DATE
DATE	00/03/07
APPROVED BY	DATE
DATE	00/03/07
MATERIAL NO.	
SEE CHART	

SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
4:1	INCH	THIRD ANGLE PROJECTION
RJ-45 INVERTED MODULAR JACK ASSEMBLY WITH RJ-11 KEEPOUT FEATURE		
MOLEX MOLEX INCORPORATED		
DOCUMENT NO.	SD-44620-001	SHEET NO. 4 OF 4
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		